

<b>PCN Number:</b>	20230208000.1	<b>PCN Date:</b>	February 08, 2023
<b>Title:</b>	Qualification of RFAB as an additional Fab site option for select LBC8 devices		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	May 8, 2023	<b>Sample requests accepted until:</b>	Mar 8, 2023*

**\*Sample requests received after March 8, 2023 will not be supported.**

**Change Type:**

<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		

**Notification Details**

**Description of Change:**

Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
MIHO8	LBC8	200 mm	RFAB	LBC8	300 mm

Qual details are provided in the Qual Data Section.

**Reason for Change:**

Continuity of supply.

**Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):**

None.

**Changes to product identification resulting from this PCN:**

**Fab Site Information:**

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
MIHO8	MH8	JPN	Ibaraki
<b>RFAB</b>	<b>RFB</b>	<b>USA</b>	<b>Richardson</b>

Sample product shipping label (not actual product label)

**Product Affected:**

ISO6720BDR	ISO6721BDR	ISO6721RBDR	ISO6721RFBDR
ISO6720FBDR	ISO6721FBDR		

**Qualification Report**  
**Approve Date 26-JANUARY -2023**

**Qualification Results**

**Data Displayed as: Number of lots / Total sample size / Total failed**

Type	#	Test Name	Condition	Duration	Qual Device: ISO6721BDR	Qual Device: ISO6720BDR
WBS	C1	Ball Shear	76 balls, 3 units min	Wires	1/76/0	-
WBP	C2	Bond Pull	76 Wires, 3 units min	Wires	1/76/0	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0

- QBS: Qual By Similarity
- Device qualified at MSL2 260C: ISO6720BDR, ISO6720FBDR, ISO6721BDR, ISO6721FBDR, ISO6721RBDR, ISO6721RFBDR.
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>

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